



Under Development	
Mass production	

RoHS

# Specification

Client Name

\_\_\_\_\_

Client P/N

\_\_\_\_\_

Product P/N

**HL-LM021H384W-12B1C24(Ra2)**

\_\_\_\_\_

Sending Date:

\_\_\_\_\_

Approval	Audit	Approval	Audit	Confirmation
				
Qualified	Disqualified	DATE:		



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LM 021 H384 W - 12 B1 C24 (Ra2)

Product line code

Ln p a oa l hpa

Chip code

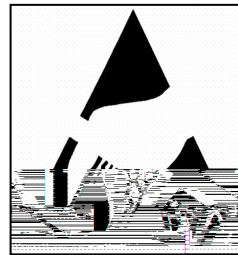
i e p e c h e d p h n o

Recommended the max power

The number of parallel  $\varnothing$   $\varnothing$

The number of series  $\varnothing$   $\varnothing$

E



OBSERVE PRECAUTIONS  
FOR HANDLING  
ELECTROSTATIC  
DISCHARGE  
SENSITIVE  
DEVICES

- Dimension 13.5mm×13.5mm×1.6mm

13.5mm×13.5mm×1.6mm

- CRI: Ra 80 80

- Wide viewing angle : 120° 120°

- RoHS compliant ROHS

- sulphation corrosion resistance

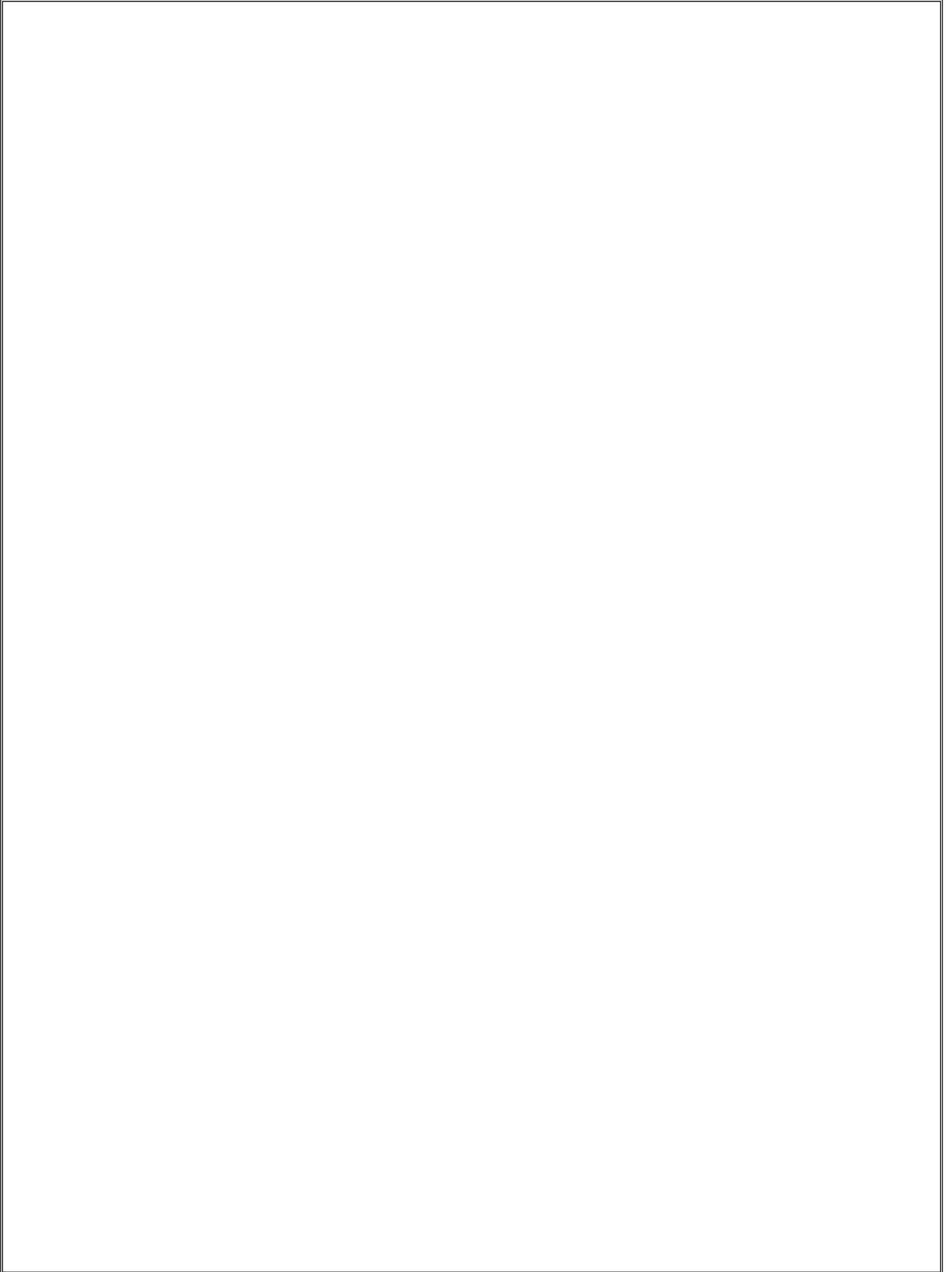
- Manual Soldering

- Down light

- Spot light

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		IF=150mA	69	75	81	—	V
	Φ	TC=2700K	—	—	—	—	lm
		TC=3000K	1050	1120	1240	99	
		TC=4000K	1100	1180	1300	104	
		TC=5000K	—	—	—	—	
		TC=5700K	1090	1160	1280	102	
		TC=6000±300K	—	—	—	—	
		TC=6500K	—	—	—	—	
		IF=150mA	80	—	—	—	—
		IF=150mA	—	3.1	—	—	W

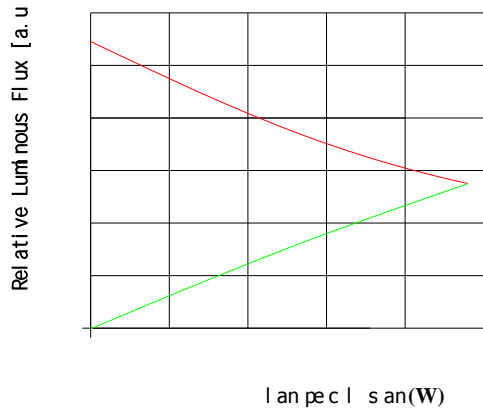

Notes for Table

\*1.Color bins are defined at IF=150mA operation. If use different forward current, it will cause the change of chromaticity and



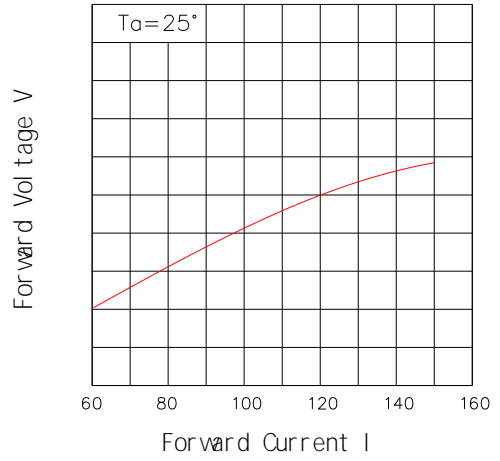
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Beam Diameter (mm)

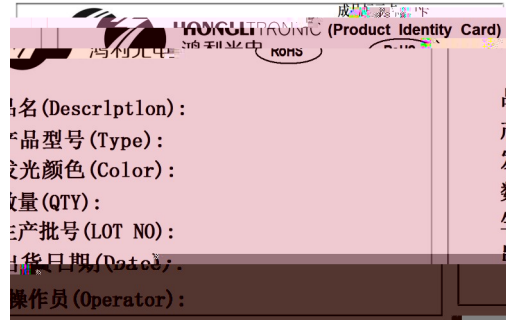
Forward Voltage vs.





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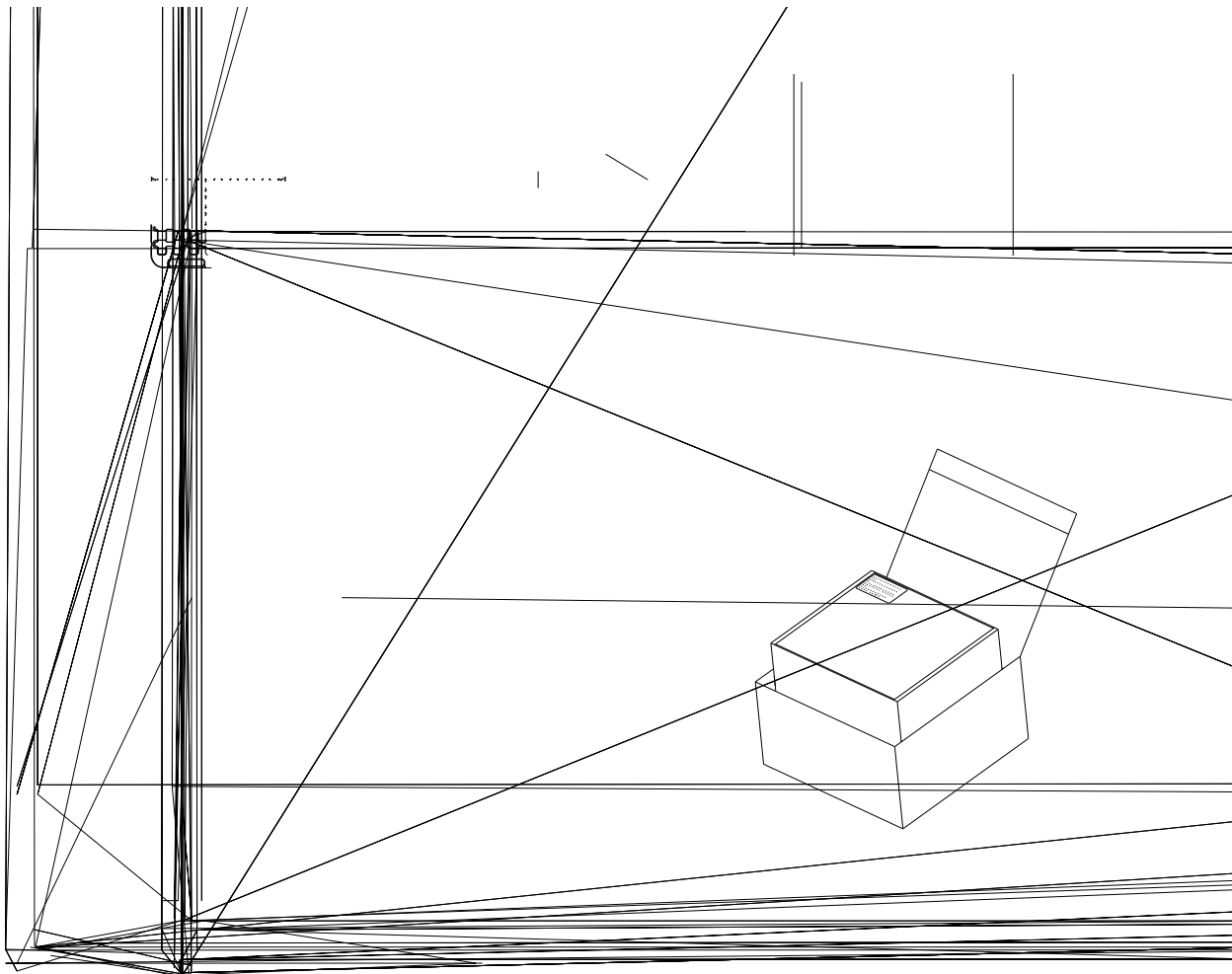
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Label on ESD shielding

Label on box

- V: Luminous Flux rank
- VF: Forward voltage rank
- TC: Color temperature
- SDCM:





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## Precaution for use ( )

### 1. Storage

To avoid moisture, we recommend storage conditions for the unopened LED +5 ~ +30 °C, relative humidity <60%. LED should be used within 168 Hrs. of opening the package. Please make sure to dehumidify and vacuum pack the remaining/ unused LED. Dehumidifying condition: +120 °C ±5 °C, 04 Hrs. Effective age for the sealed led is one year.

### 2. The soldering precautions

Soldering conditions: Reflow soldering is not recommended for this LED and soldering, soldering iron temperature at 350°C and soldering time not More than 5 seconds, after the first soldering, make sure the substrate surface temperature returns to ambient temperature before a second soldering. Please make sure when soldering, there is no external force on the soldering surface and silicon batardeau (such as pressure, friction or sharp metal nails, etc.), to avoid gold wire deformation or damage and other abnormalities. If beyond recommended conditions, we cannot guarantee the LED stability, please do the risk assessment first.

During assembly, please ensure that a good quality thermal paste is applied and distributed evenly over the surface. While using thermal pad (Heat Sink), make sure LED is firmly tightened and there is no gap between surfaces. In such media products, through a pressure test of at least 500 volts

### 3. Anti-Static Measures

Please take adequate measures to prevent electrostatic generation, such as wearing electrostatic ring or anti-static fingerstall etc; any relative products like plant equipment, machinery, carrier and transportation units shall be connected with ground. Please make sure when

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#### 4. Temperature Control

The temperature of Aluminum PCB do not exceed 95 if the input power reach 80% max Pi, the temperature of Aluminum PCB should be control below 85COB recommendation colloid surface temperature control 160 .

95

80%

85

#### 5. The drive control :

Drive this product at constant current. Output current ranges specifications should be according to the operational and other conditions, as mentioned in data sheet. Before using a constant voltage source or altered specifications other than recommended, please consider risk factors.

#### 6. Other

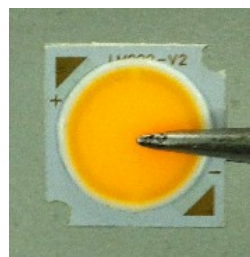
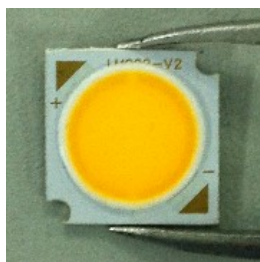
Product is not suitable to use in following conditions

- Direct or indirect wet / damp conditions, such as rain, etc.;
- 
- In contact with sea water and erosive materials
- 
- Exposed to corrosive gases (e.g., Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>x</sub>, NO<sub>x</sub>, etc.);
- ( Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>x</sub>, NO<sub>x</sub> )
- Exposed to dust, liquids or oils;
- 

— COB

2000PPM

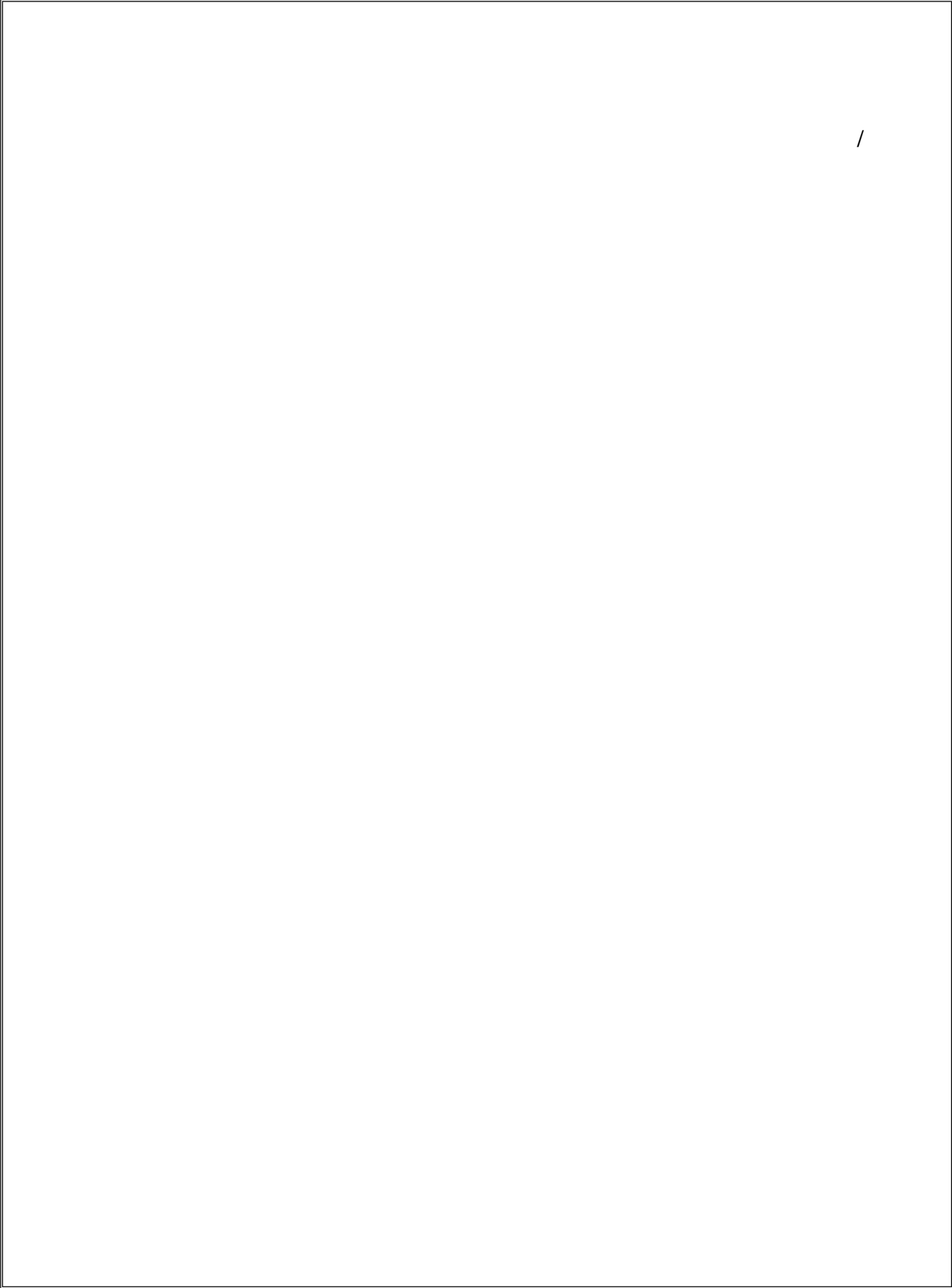
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